

MBF Plastic-Encapsulate Bridge Rectifier

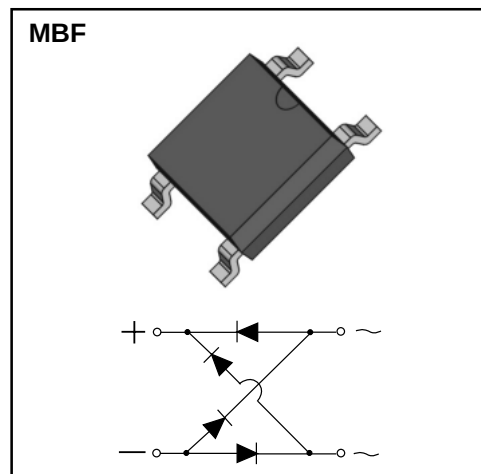
Single Phase 1.0Amp Schottky Bridge Rectifiers

Features

- I_O 1.0A
- VRRM 20V -200V
- Low forward voltage drop
- High surge current capability

Mechical Data

- Case: MBF molded plastic
- Molding compound: UL flammability classification rating 94V-0
- Terminals: Solder plated, solderable per MIL- STD-202, Method 208
- Polarity: As marked on case



Parameter	SYMBOLS	KMB 12F	KMB 14F	KMB 16F	KMB 18F	KMB 110F	KMB 115F	KMB 120F	UNITS
Maximum repetitive peak reverse voltage	V _{RRM}	20	40	60	80	100	150	200	V
Maximum RMS voltage	V _{RMS}	14	28	42	56	70	70	140	V
Maximum DC blocking voltage	V _{DC}	20	40	60	80	100	150	200	V
Maximum average forward rectified current at T _L =100°C On glass-epoxy P.C.B (Note 1)	I _(AV)	1.0							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	30.0							A
Rating for fusing (t=8.3ms, T _a =25°C)	I ² _t	3.7							A ² _s
Maximum instantaneous forward voltage at 1.0A	V _F	0.55		0.7	0.85		0.95		V
Maximum DC reverse current T _A =25°C at rated DC blocking voltage T _A =125°C	I _R	0.5 50			0.2 20			mA	
Typical thermal resistance	R _{qJA}	80.0							°C/W
Operating junction temperature range	T _J	-55 to +125			-55 to +150				°C
Storage temperature range	T _{STG}	-55 to +150							°C

Note:1.Mounted on glass epoxy PC board with 1.3*1.3mm solder pad

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

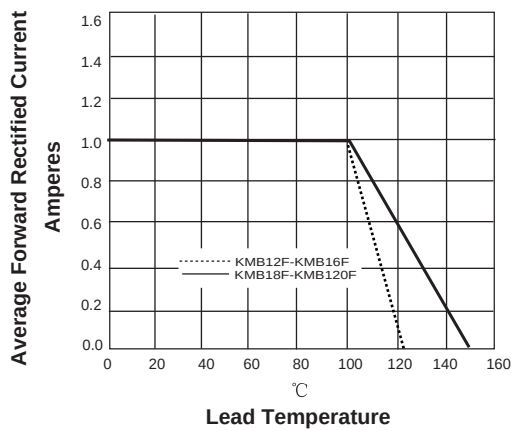


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

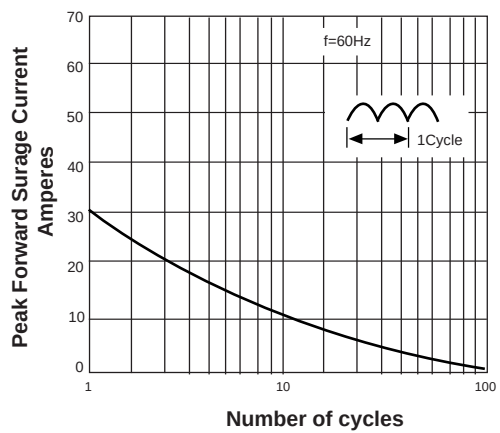


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

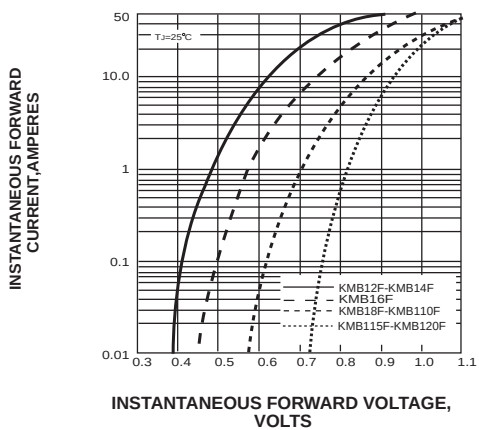
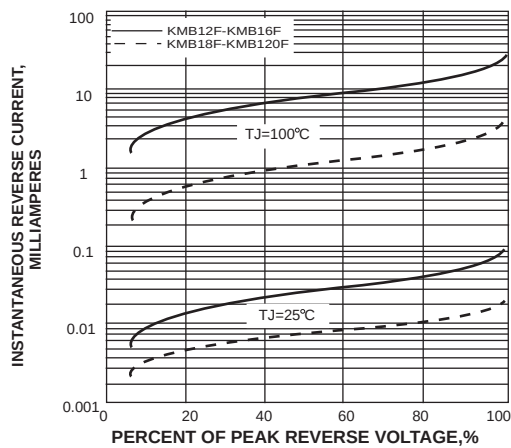
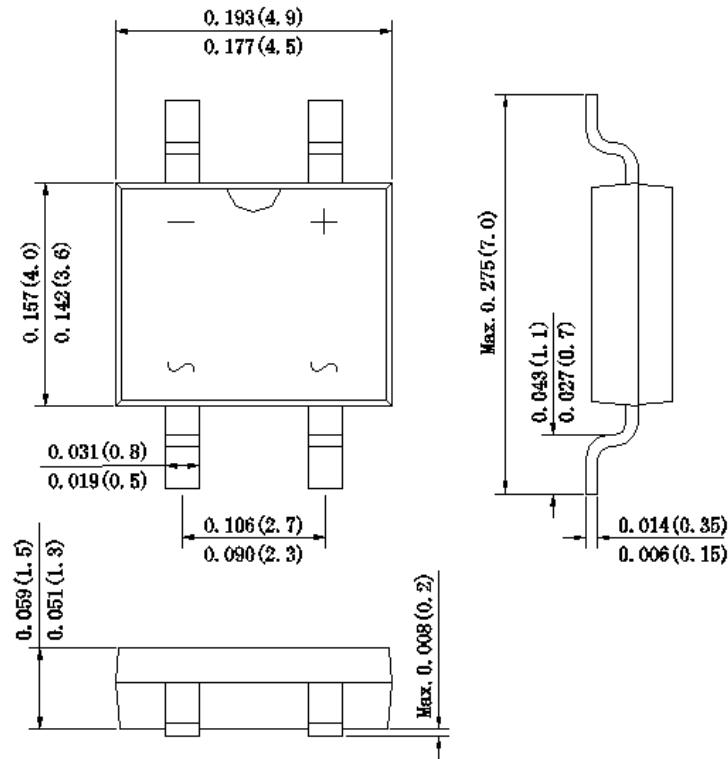


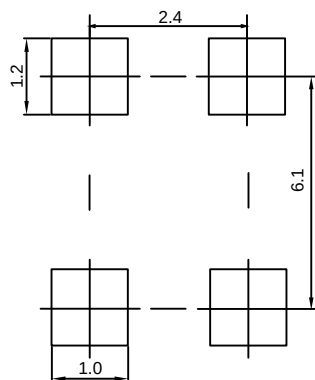
FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



MBF Package Outline Dimensions



MBF Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

NOTICE

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Reel Taping Specifications For Surface Mount Devices-MBF

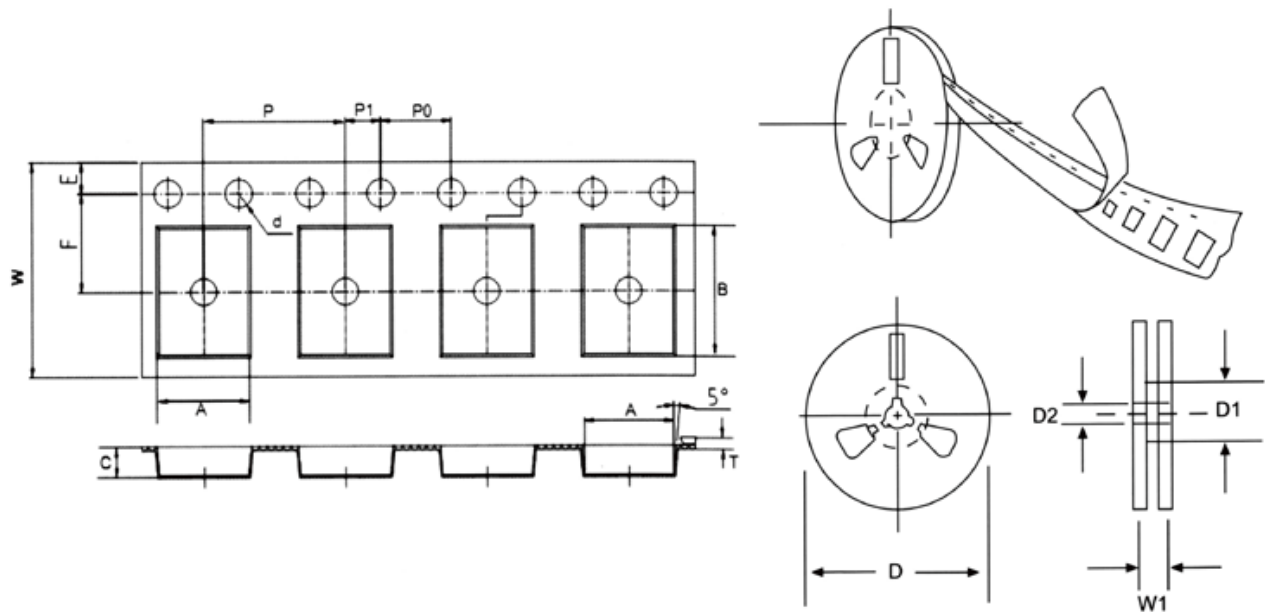


FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	MBF mm(inch)
Carrier width	A	5.02±0.1(0.198±0.004)
Carrier length	B	7.15±0.1(0.281±0.004)
Carrier depth	C	1.65±0.1(0.074±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	279±2.0 (11± 0.079)
Reel inner diameter	D1	75 ±1.0 (2.95 ±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Sprocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.50±0.1(0.217±0.002)
Punch hole pitch	P	8.0±0.1(0.315±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Totall tape thickness	T	0.20-0.70(0.008-0.028)
Tape width	W	12.0±0.3/-0.1(0.472±0.004)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE: Devices are packde in accordance with EIA standard RS-481-A and specification given above.